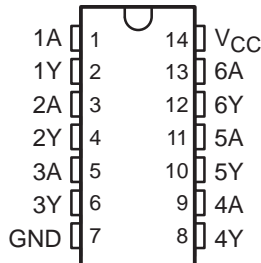


# SN54HC05, SN74HC05 HEX INVERTERS WITH OPEN-DRAIN OUTPUTS

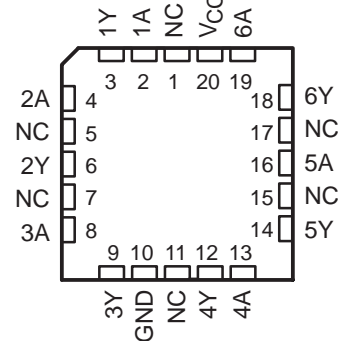
SCLS080D – MARCH 1984 – REVISED AUGUST 2003

- Wide Operating Voltage Range of 2 V to 6 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 20- $\mu$ A Max  $I_{CC}$
- Typical  $t_{pd} = 8$  ns
- $\pm 4$ -mA Output Drive at 5 V
- Low Input Current of 1  $\mu$ A Max

SN54HC05 . . . J OR W PACKAGE  
SN74HC05 . . . D, DB, N, NS, OR PW PACKAGE  
(TOP VIEW)



SN54HC05 . . . FK PACKAGE  
(TOP VIEW)



NC – No internal connection

## description/ordering information

The 'HC05 devices contain six independent inverters. They perform the Boolean function  $Y = \bar{A}$  in positive logic. The open-drain outputs require pullup resistors to perform correctly. They may be connected to other open-drain outputs to implement active-low wired-OR or active-high wired-AND functions.

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube of 25	SN74HC05N	SN74HC05N
		Tube of 50	SN74HC05D	HC05
	SOIC – D	Reel of 2500	SN74HC05DR	
		Reel of 250	SN74HC05DT	
	SOP – NS	Reel of 2000	SN74HC05NSR	
	SSOP – DB	Reel of 2000	SN74HC05DBR	HC05
-55°C to 125°C	TSSOP – PW	Reel of 2000	SN74HC05PWR	HC05
		Reel of 250	SN74HC05PWT	
	CDIP – J	Tube of 25	SNJ54HC05J	SNJ54HC05J
	CFP – W	Tube of 150	SNJ54HC05W	SNJ54HC05W
	LCCC – FK	Tube of 55	SNJ54HC05FK	SNJ54HC05FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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 **TEXAS  
INSTRUMENTS**

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**SN54HC05, SN74HC05**  
**HEX INVERTERS**  
**WITH OPEN-DRAIN OUTPUTS**  
 SCLS080D – MARCH 1984 – REVISED AUGUST 2003

**FUNCTION TABLE**  
 (each inverter)

INPUT A	OUTPUT Y
H	L
L	H

**logic diagram (positive logic)**



**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Supply voltage range, $V_{CC}$	-0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	$\pm 20$ mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1)	$\pm 20$ mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	$\pm 25$ mA
Continuous current through $V_{CC}$ or GND	$\pm 50$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 2):	
D package	86°C/W
DB package	96°C/W
N package	80°C/W
NS package	76°C/W
PW package	113°C/W
Storage temperature range, $T_{stg}$	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
 2. The package thermal impedance is calculated in accordance with JESD 51-7.

**recommended operating conditions (see Note 3)**

		SN54HC05			SN74HC05			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
$V_{CC}$	Supply voltage	2	5	6	2	5	6	V
$V_{IH}$	High-level input voltage	$V_{CC} = 2$ V		1.5	1.5		V	
		$V_{CC} = 4.5$ V		3.15	3.15			
		$V_{CC} = 6$ V		4.2	4.2			
$V_{IL}$	Low-level input voltage	$V_{CC} = 2$ V			0.5	0.5	V	
		$V_{CC} = 4.5$ V			1.35	1.35		
		$V_{CC} = 6$ V			1.8	1.8		
$V_I$	Input voltage	0		$V_{CC}$	0	$V_{CC}$	V	
$V_O$	Output voltage	0		$V_{CC}$	0	$V_{CC}$	V	
$\Delta t/\Delta v$	Input transition rise/fall time	$V_{CC} = 2$ V			1000	1000	ns	
		$V_{CC} = 4.5$ V			500	500		
		$V_{CC} = 6$ V			400	400		
$T_A$	Operating free-air temperature	-55		125	-40	85	°C	

NOTE 3: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



**SN54HC05, SN74HC05**  
**HEX INVERTERS**  
**WITH OPEN-DRAIN OUTPUTS**

SCLS080D – MARCH 1984 – REVISED AUGUST 2003

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54HC05		SN74HC05		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
I <sub>OH</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> , V <sub>O</sub> = V <sub>CC</sub>	6 V		0.01	0.5		10		5	μA
V <sub>OL</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 20 μA	2 V	0.002	0.1		0.1		0.1	V
			4.5 V	0.001	0.1		0.1		0.1	
		6 V	0.001	0.1		0.1		0.1		
		I <sub>OL</sub> = 4 mA	4.5 V	0.17	0.26		0.4		0.33	
		I <sub>OL</sub> = 5.2 mA	6 V	0.15	0.26		0.4		0.33	
I <sub>I</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0	6 V		±0.1	±100		±1000		±1000	nA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0, I <sub>O</sub> = 0	6 V			2		40		20	μA
C <sub>i</sub>		2 V to 6 V		3	10		10		10	pF

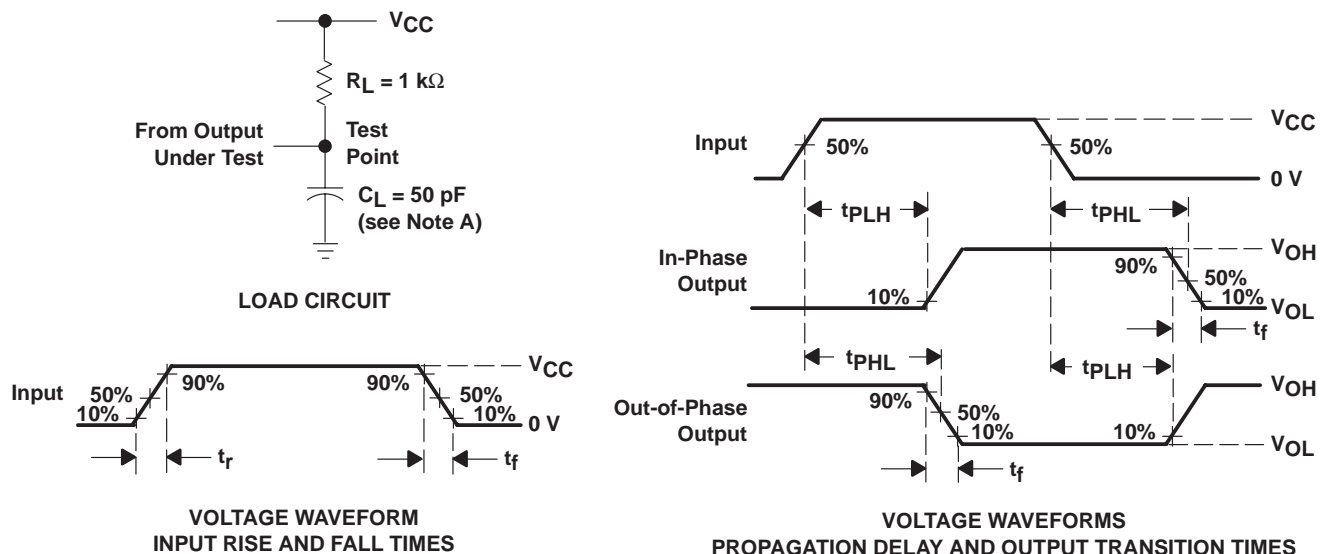
**switching characteristics over recommended operating free-air temperature range, C<sub>L</sub> = 50 pF (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54HC05		SN74HC05		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A	Y	2 V		60	115		175		145	ns
			4.5 V		13	23		35		29	
			6 V		10	20		30		25	
t <sub>PHL</sub>	A	Y	2 V		45	85		130		105	ns
			4.5 V		9	17		26		21	
			6 V		8	14		22		18	
t <sub>f</sub>		Y	2 V		38	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	

**operating characteristics, T<sub>A</sub> = 25°C**

PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub> Power dissipation capacitance per inverter	No load	20	pF

PARAMETER MEASUREMENT INFORMATION



- NOTES: A.  $C_L$  includes probe and test-fixture capacitance.  
 B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1$  MHz,  $Z_O = 50 \Omega$ ,  $t_r = 6$  ns,  $t_f = 6$  ns.  
 C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-88718012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8871801CA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN54HC05J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN74HC05D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC05DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC05DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC05DBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC05DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC05DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC05DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC05DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC05DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC05DT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC05DTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC05DTG4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC05N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC05N3	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI
SN74HC05NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC05NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC05NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC05NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC05PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC05PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC05PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC05PWT	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC05PWTE4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC05PWTG4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
no Sb/Br)								
SNJ54HC05FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54HC05J	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

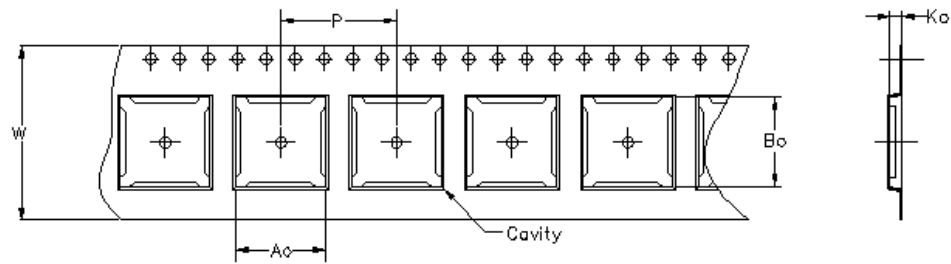
**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

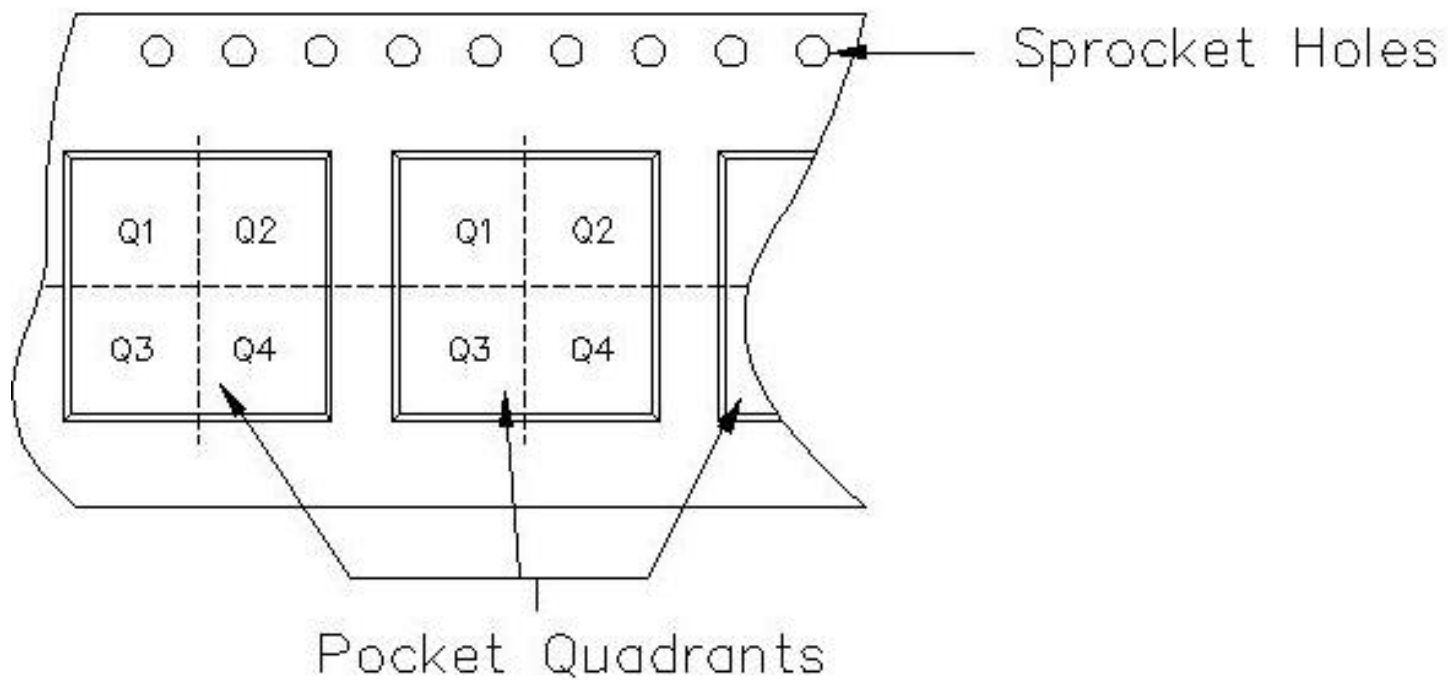
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Carrier tape design is defined largely by the component length, width, and thickness.

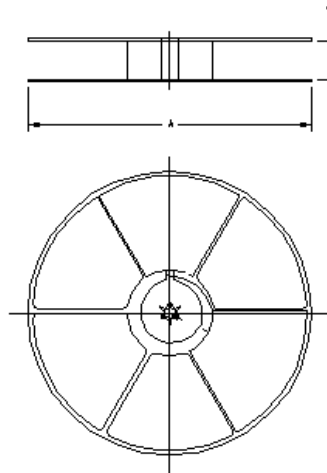
$A_o$ = Dimension designed to accommodate the component width.
$B_o$ = Dimension designed to accommodate the component length.
$K_o$ = Dimension designed to accommodate the component thickness.
$W$ = Overall width of the carrier tape.
$P$ = Pitch between successive cavity centers.



**TAPE AND REEL INFORMATION**

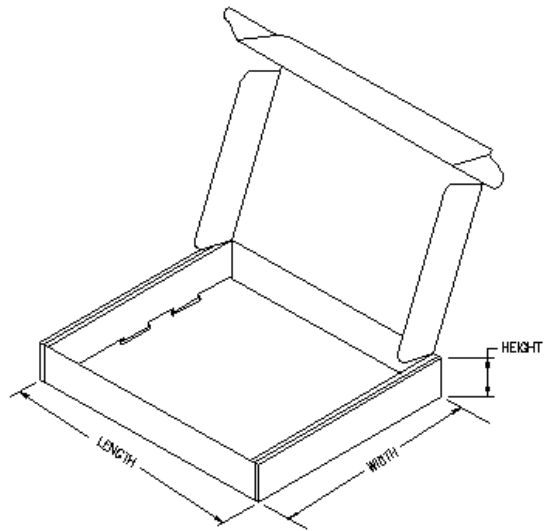


Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC05DBR	DB	14	MLA	330	16	8.2	6.6	2.5	12	16	Q1
SN74HC05DR	D	14	FMX	330	16	6.5	9.0	2.1	8	16	Q1
SN74HC05DR	D	14	MLA	330	16	6.5	9.0	2.1	8	16	Q1
SN74HC05NSR	NS	14	MLA	330	16	8.2	10.5	2.5	12	16	Q1
SN74HC05PWR	PW	14	MLA	330	12	7.0	5.6	1.6	8	12	Q1



**TAPE AND REEL BOX INFORMATION**

Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74HC05DBR	DB	14	MLA	342.9	336.6	28.58
SN74HC05DR	D	14	FMX	342.9	336.6	28.58
SN74HC05DR	D	14	MLA	342.9	336.6	28.58
SN74HC05NSR	NS	14	MLA	342.9	336.6	28.58
SN74HC05PWR	PW	14	MLA	342.9	336.6	20.64



J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



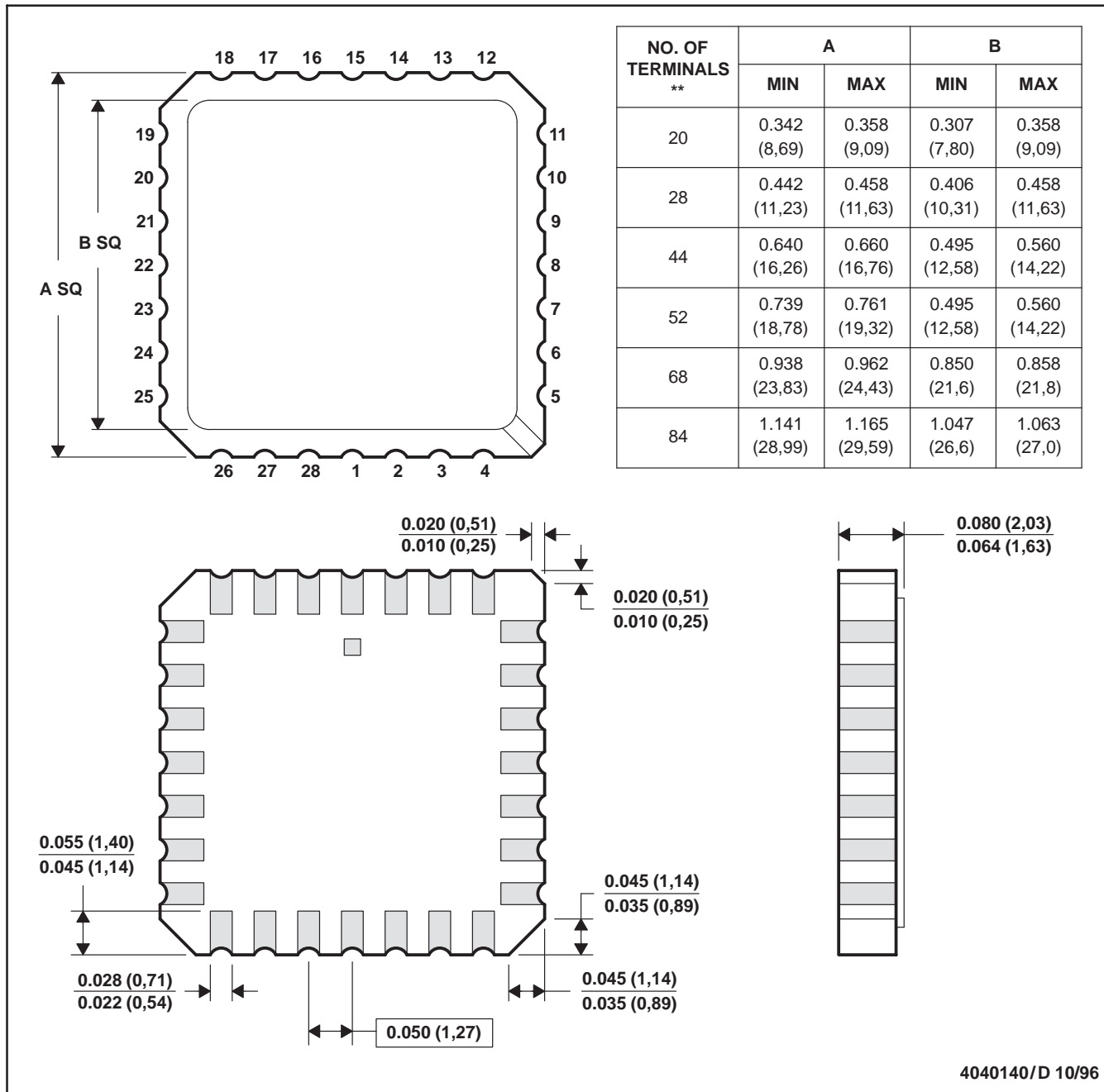
4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
  - This drawing is subject to change without notice.
  - This package is hermetically sealed with a ceramic lid using glass frit.
  - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N\*\*)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. This package can be hermetically sealed with a metal lid.  
 D. The terminals are gold plated.  
 E. Falls within JEDEC MS-004

N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

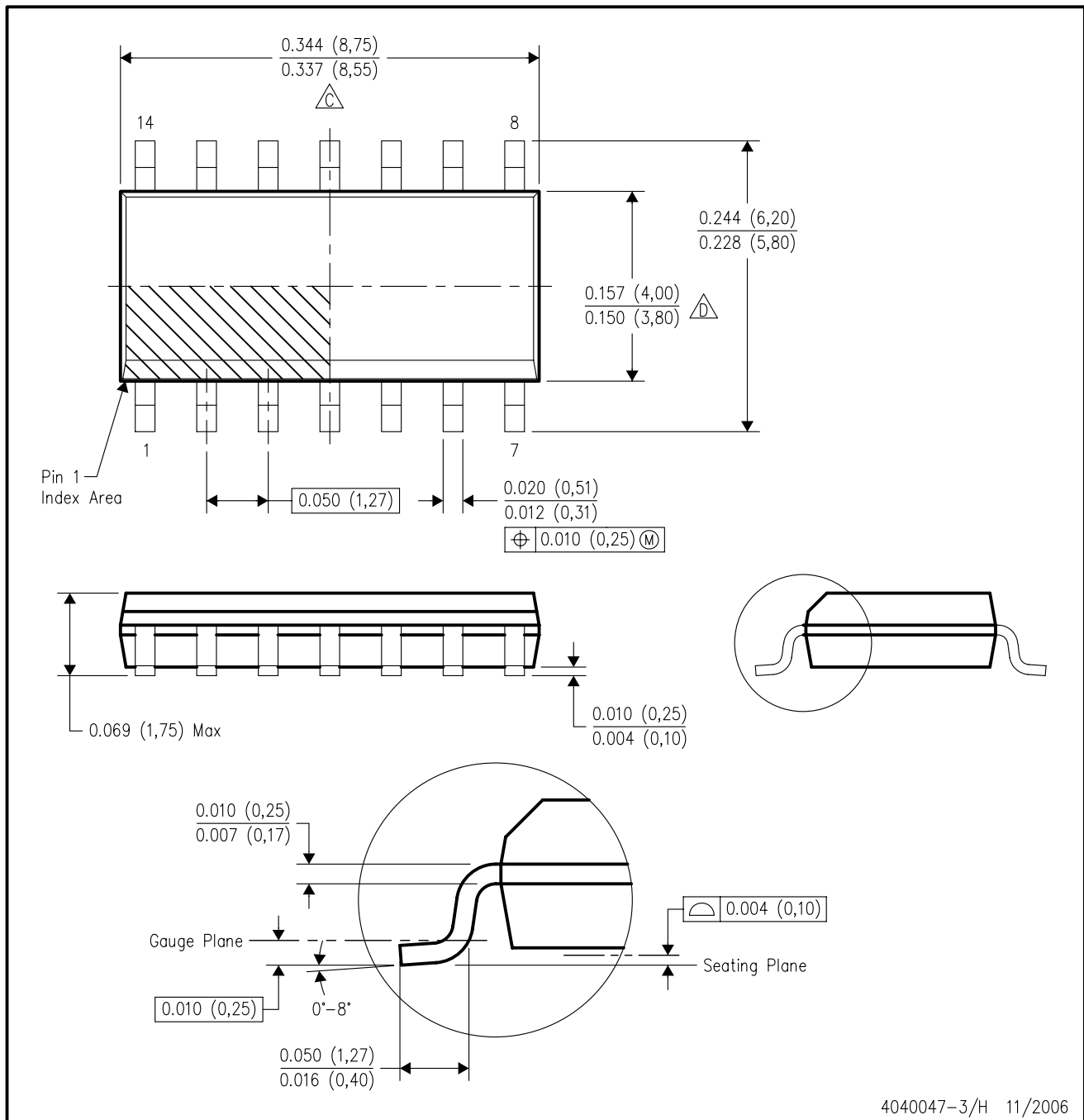
16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
  - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



4040047-3/H 11/2006

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - $\triangle C$  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
  - $\triangle D$  Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
  - E. Reference JEDEC MS-012 variation AB.

## MECHANICAL DATA

**NS (R-PDSO-G\*\*)**

**PLASTIC SMALL-OUTLINE PACKAGE**

**14-PINS SHOWN**



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150



PW (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153